

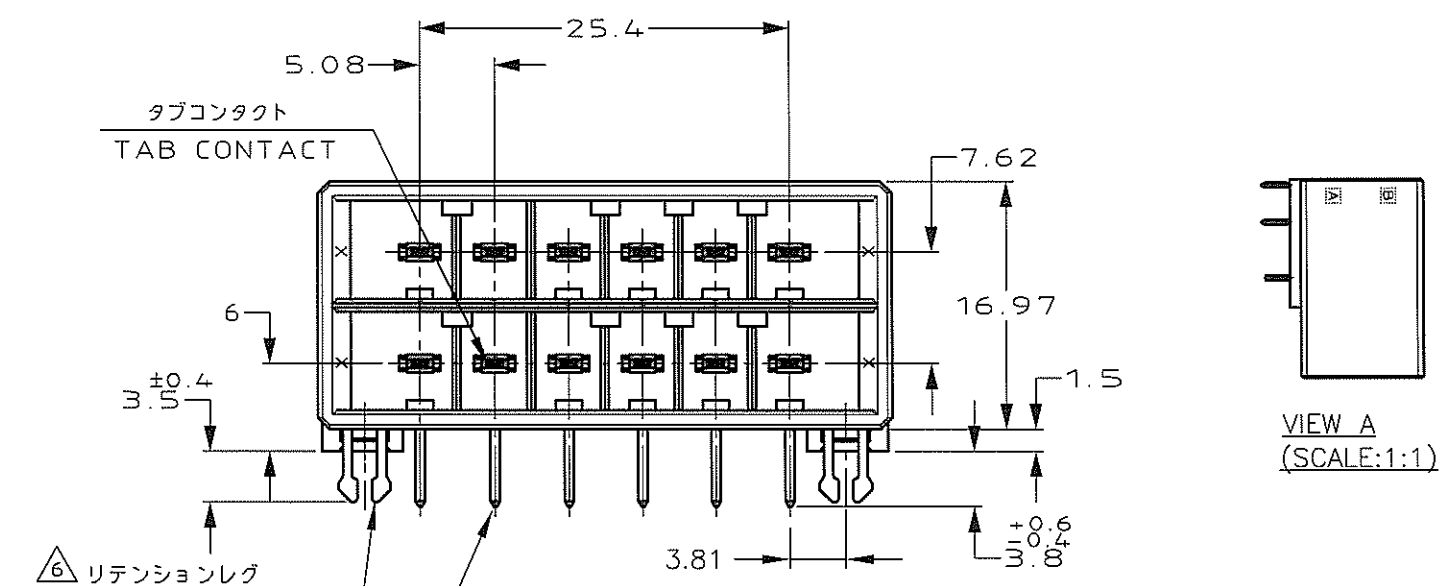
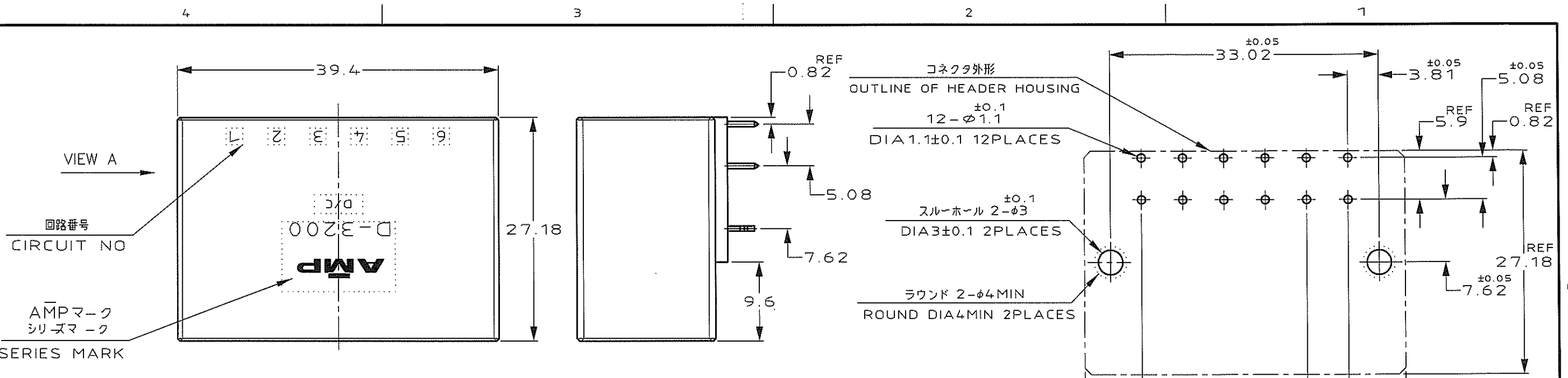
NUMBER 316081

3rd ANGLE PROJECTION

METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

- 注記
- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒
コンタクト: 銅合金
リテンションレグ: 銅合金
 - めっき: コンタクト: 全面Ni下地
接触部: 0.38µm MIN金めっき
 - めっき: コンタクト: 全面Ni下地
接触部: 0.76µm MIN金めっき
 - めっき: コンタクト: 全面Ni下地
接触部: 2.0 µm MINスズめっき
 - めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき
 - めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上にスズめっき
- NOTES
- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
 - FINISH (CONTACT AREA): 0.38µm MIN GOLD PLATING OVER Ni PLATING
 - FINISH (CONTACT AREA): 0.76µm MIN GOLD PLATING OVER Ni PLATING
 - FINISH (CONTACT AREA): 2.0 µm MIN TIN PLATED OVER NICKEL
 - FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
 - FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
 - OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

KEYING LOCATION	A ROW KEYING	B ROW KEYING	FINISH	製品番号	PART NO.
	X	Y	△6 △4	3-316081-5	△7
	X	Y	△6 △3	3-316081-3	
	X	Y	△6 △2	3-316081-2	
	Y	Y	△6 △4	2-316081-5	
	Y	Y	△6 △3	2-316081-3	
	Y	Y	△6 △2	2-316081-2	
	X	X	△6 △4	1-316081-5	
	X	X	△6 △3	1-316081-3	
	X	X	△6 △2	1-316081-2	

B4	REVISED PER ECO-11-005030	RK	HMR	20MAR 11
LTR	REVISION RECORD	DR	CHK	DATE

DR. 4/JUL/95 K.IKEDA	DE. 4/JUL/95 K.IKEDA
CHK. 4/JUL/95 Y.ISHIKAWA	APP. 4/JUL/95 S.MANABE

WIRE RANGE		INSULATION DIA		NAME	
mm²(AWG)		mmφ		12 POS DOUBLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
10±0.3		10±0.4		SIZE	LOC
30±0.45		30±0.45		A3	J
角差: ±3'		角差: ±3'		NUMBER	REV.
				C-316081	B4
				SCALE	SHEET
				2-1	1 OF 1

Mouser Electronics

Authorized Distributor

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[1-316081-3](#)